- Delay Elements for Generating Delay Lines
- Inverting and Non-inverting Elements
- Buffer NAND Elements Rated at IOL of 12/24 mA
- PNP Inputs Reduce Fan-In (I<sub>IL</sub> = -0.2 mA MAX)
- Worst Case MIN/MAX Delays Guaranteed Across Temperature and VCC Ranges

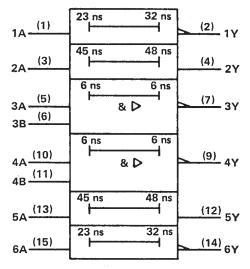
#### description

These 'LS31 delay elements are intended to provide well-defined delays across both temperature and  $V_{\rm CC}$  ranges. Used in cascade, a limitless range of delay gating is possible.

All inputs are PNP with I $_{\rm IL}$  MAX of -0.2 mA. Gates 1, 2, 5, and 6 have standard Low-Power Schottky output sink current capability of 4 and 8 mA I $_{\rm OL}$ . Buffers 3 and 4 are rated at 12 and 24 mA.

The SN54LS31 is characterized for operation over the full military temperature range of  $-55\,^{\circ}\text{C}$  to  $125\,^{\circ}\text{C}$ . The SN74LS31 is characterized for operation from  $0\,^{\circ}\text{C}$  to  $70\,^{\circ}\text{C}$ .

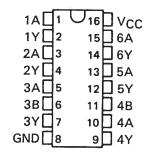
# logic symbol†



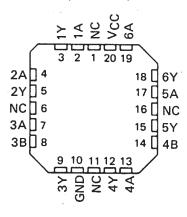
<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54LS31 . . . J OR W PACKAGE SN74LS31 . . . D OR N PACKAGE (TOP VIEW)



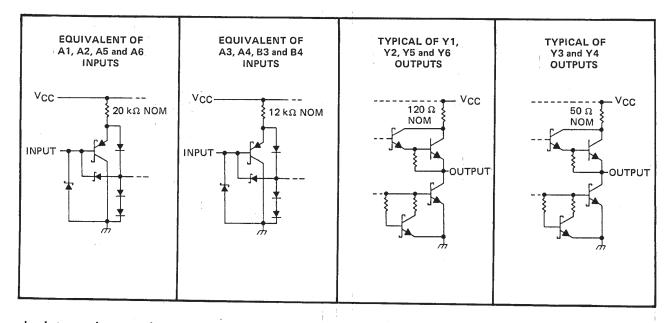
SN54LS31 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



Delay Element	Logic	T.	ypical De	Description of the second	
	Logic	<sup>t</sup> PLH	<sup>t</sup> PHL	AVG.	Rated IOL
Gates 1 and 6	Inverting	32 ns	23 ns	27.5 ns	4 and 8 mA
Gates 2 and 5	Non-Inverting	45 ns	48 ns	46.5 ns	4 and 8 mA
Buffers 3 and 4	2-Input NAND	6 ns	6 ns	6 ns	12 and 24 mA



# absolute maximum ratings over operating free air temperature range (unless otherwise noted)

Supply voltage, VCC (See Note 1)	7 V
Input voltage, V <sub>I</sub> : All inputs	7 \/
Operating free-air temperature range: SN54LS31 5	55° C to 125° C
SN74LS31	. 0°C to 70°C
Storage temperature range	5°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

## recommended operating conditions

			SN54LS31		SN74LS31				
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	55	4.75	5	5.25	V
$V_{IH}$	H High-level input voltage					2	*************		V
$V_{IL}$	Low-level input voltage	u-level input voltage			0.7			0.8	V
ЮН	High-level output current	Y3, Y4 outputs			- 1.2			- 1.2	
.Оп	- Tright Towar output current	All other outpus			- 0.4			- 0.4	mA
IOL Low-level output current		Y3, Y4 outputs	12				24		
IOL		All other outputs	4				8	- mA	
$T_A$	Operating free-air temperature		- 55		125	0		70	°C



# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	NDITIONS†			SN54LS31			SN74LS31				
	1201 00			MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT		
VIK	$V_{CC} = MIN$ , $I_1 = -18 \text{ mA}$					- 1.5			- 1.5	V		
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V,	Y3, Y4	I <sub>OH</sub> = - 1.2 mA	2.4	3.1		2.4	3.1				
-01	VIL = MAX	Others	I <sub>OH</sub> = - 0.4 mA	2.5	3.1	***************************************	2.7	3.1		\ \		
		Y3, Y4	IOL = 12 mA		0.25	0.4		0.25	0.4			
VOL	VCC = MIN, VIH = 2 V,	13, 14	IOL = 24 mA					0.35	0.5	1		
· OL	VIL = MAX	Others	I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	\ \		
	I <sub>OL</sub> = 8 mA		I <sub>OL</sub> = 8 mA					0.35	0.5	1		
Ц.	$V_{CC} = MAX$ , $V_I = 7 V$					0.1			0.1	mA		
ЧН	V <sub>CC</sub> = MAX, \V <sub>I</sub> = 2.7 V					20			20	μΑ		
ηц	$V_{CC} = MAX$ , $V_I = 0.4 V$					- 0.2			- 0.2	mA		
	V <sub>CC</sub> = MAX, (A3, A4, B3, B4	= 0 V	Y3, Y4	- 30	····	- 130	- 30		- 130	<b> </b>		
los§	V <sub>CC</sub> = MAX, A1, A6 = 0 V, A2, A5 = 4.5 V		Y1, Y2, Y5, Y6	- 20		- 100	- 20		<b>–</b> 100	mA		
ICC ICCH	V <sub>CC</sub> = MAX, A2, A5 = 4.5 V,	all other i	inputs 0 V		2.3	4		2.3	4			
ICCL	$V_{CC} = MAX$ , $A2$ , $A5 = 0$ V, all other inputs 4.5 V				13	20		13	20	mA		

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

## switching characteristics, (see note 2)

PARAMETER	FROM	ТО	SN54LS31		S	SN74LS31		
	(INPUT)	(OUTPUT)	MIN TY	P MAX	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	A1, A6	Y1, Y6	15	70	22		65	ns
tPHL		T 1, TO	9	50	13		45	ns
<sup>t</sup> PLH	A2, A5	V2 V5	22	90	31		80	ns
tPHL	A2, A0	Y2, Y5	20	105	30		95	ns
<sup>t</sup> PLH	A3, B3, A4,	V0 V4	2	20	2		15	ns
<sup>t</sup> PHL	Y4	Y3, Y4	2	20	2		15	ns

NOTE 2:  $V_{CC}$  = MIN to MAX  $R_L$  = 667  $\Omega$ ,  $C_L$  = 45 pF for Y3 and Y4.  $R_L$  = 2 k $\Omega$ ,  $C_L$  = 15 pF for Y1, Y2, Y5 and Y6.  $T_A$  = MIN to MAX

Load circuits and voltage waveforms are shown in Section 1.

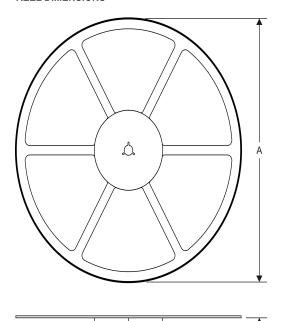
<sup>§</sup> Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

# PACKAGE MATERIALS INFORMATION

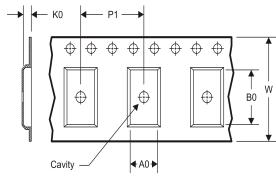
www.ti.com 14-Jul-2012

### TAPE AND REEL INFORMATION

#### **REEL DIMENSIONS**







A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### TAPE AND REEL INFORMATION

\*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS31NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

www.ti.com 14-Jul-2012



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS31NSR	SO	NS	16	2000	367.0	367.0	38.0

#### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

roducts		Applications
udia	ununu ti com/ou dio	Automotive on

Pr

Audio Automotive and Transportation www.ti.com/automotive www.ti.com/audio www.ti.com/communications **Amplifiers** amplifier.ti.com Communications and Telecom **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** Consumer Electronics www.ti.com/consumer-apps www.dlp.com DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic logic.ti.com Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Mobile Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity www.ti.com/wirelessconnectivity